

## Title (en)

Electrical device, particularly relay socket, with spring clip and method of manufacture

## Title (de)

Elektrisches Bauteil, insbesondere Relaisfassung, mit Federklemmen und Verfahren zu seiner Herstellung

## Title (fr)

Élément électrique, notamment support de relais, avec borne élastique et procédé de fabrication

## Publication

**EP 1777720 A1 20070425 (DE)**

## Application

**EP 05023154 A 20051024**

## Priority

EP 05023154 A 20051024

## Abstract (en)

Electrical device (1) has a housing (11) having a terminal (5) provided with an insertion opening (6) configured for receiving a conductor end (13). The insertion opening communicates with an assembly chamber (14) formed in the terminal. A clamp (12) is arranged in the assembly chamber. The clamp has a leaf spring (15) divided into two parallel spring contacts (21, 22) by a parting slot. Each spring contacts is deflectable in a direction of insertion of the conductor end and having a free end (24, 25) positioned adjacent to a contact pressure plate so that a clamping slot is formed there between that force-fittingly receives the conductor end. The electrical device is a relay socket. An independent claim is included for a method of manufacture.

## IPC 8 full level

**H01H 50/14** (2006.01); **H01R 4/48** (2006.01)

## CPC (source: EP US)

**H01H 50/14** (2013.01 - EP US); **H01R 4/48275** (2023.08 - EP US); **H01R 9/26** (2013.01 - EP US); **H01R 43/20** (2013.01 - EP US)

## Citation (search report)

- [XY] DE 7801829 U1 19810611
- [YX] EP 1515397 A1 20050316 - WEIDMUELLER INTERFACE [DE]
- [Y] DE 20205821 U1 20030821 - WEIDMUELLER INTERFACE [DE]
- [A] DE 29806097 U1 19980618 - GOERLITZ ESG GMBH [DE]

## Cited by

EP3722916A3; CN109830406A; WO2016166132A1; WO2013091846A1; WO2009030719A1; EP2201609B1

## Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

## Designated extension state (EPC)

AL BA HR MK YU

## DOCDB simple family (publication)

**EP 1777720 A1 20070425**; **EP 1777720 B1 20080604**; AT E397786 T1 20080615; CN 1988263 A 20070627; CN 1988263 B 20100825; DE 502005004350 D1 20080717; DK 1777720 T3 20081006; ES 2310313 T3 20090101; JP 2007123272 A 20070517; JP 5025223 B2 20120912; PL 1777720 T3 20081128; US 2007093121 A1 20070426; US 7344422 B2 20080318

## DOCDB simple family (application)

**EP 05023154 A 20051024**; AT 05023154 T 20051024; CN 200610140369 A 20061024; DE 502005004350 T 20051024; DK 05023154 T 20051024; ES 05023154 T 20051024; JP 2006288372 A 20061024; PL 05023154 T 20051024; US 55192106 A 20061023